

XI'AN IR-PERI



Company

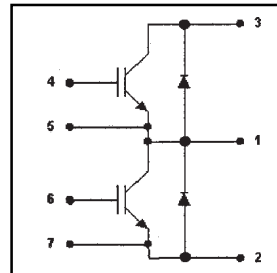
PRELIMINARY

GA200TF60K

“ HALF-BRODGE” IGBT DOUBLE INT-A -PAK

Features

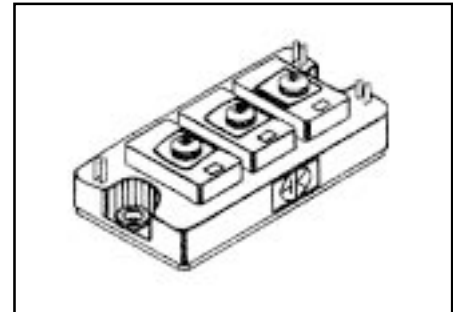
- GEN5 NPT Technology
- Low Vce(on)
- 10us Short Circuit Capability
- Square RBSOA
- Positive Vce(on) Temperature Coefficient
- HEXFRED™ antiparallel diodes with ultra- soft recovery
- Industry standard package



V<sub>CES</sub>=600V  
 V<sub>CE(on) typ.</sub>=1.70V  
 @V<sub>GE</sub>=15V,I<sub>c</sub>=150A

Benefits

- Increased operating efficiency
- Rugged Transient Performance
- Performance optimized for power conversion: UPS, SMPS, Welding;Benchmark Efficiency for Motor Control Applications
- Excellent Current Sharing in Parallel Operation
- Lower EMI, requires less snubbing



Absolute Maximum Ratings

Parameter		Max.	Units
V <sub>CES</sub>	Collector- to- Emitter Voltage	600	V
I <sub>c @ Tc=25°C</sub>	Continuous Collector Current	200	
I <sub>c @ Tc=85°C</sub>	Continuous Collector Current	200	
I <sub>CM</sub>	Pulsed collector Current	400	A
I <sub>LM</sub>	Peak switching Current	400	
I <sub>FM</sub>	Peak Diode Forward Current	400	
V <sub>GE</sub>	Gate- to- Emitter Voltage	± 20	V
V <sub>ISOL</sub>	RMS Isolation Voltage, Any Terminal To Case, t =1 min	2500	
P <sub>D @ Tc=25°C</sub>	Maximum Power Dissipation	625	W
P <sub>D @ Tc=85°C</sub>	Maximum Power Dissipation	325	
T <sub>J</sub>	Operating Junction Temperature Range	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature Range	-40 to +125	

Thermal / Mechanical Characteristics

Parameter		Typ.	Max.	Units
R <sub>θJC</sub>	Thermal Resistance, Junction-to- Case- IGBT	-	0.20	°C/W
R <sub>θJC</sub>	Thermal Resistance, Junction-to- Case- Diode	-	0.35	
R <sub>θCS</sub>	Thermal Resistance, Case-to- Sink- Module	0.1		-
	Mouting Torque, Case-to-Heatsink	-	4.0	N.m
	Mouting Torque, Case-to-Terminal 1,2 & 3	-	3.0	
	Weight of Module	300	-	g

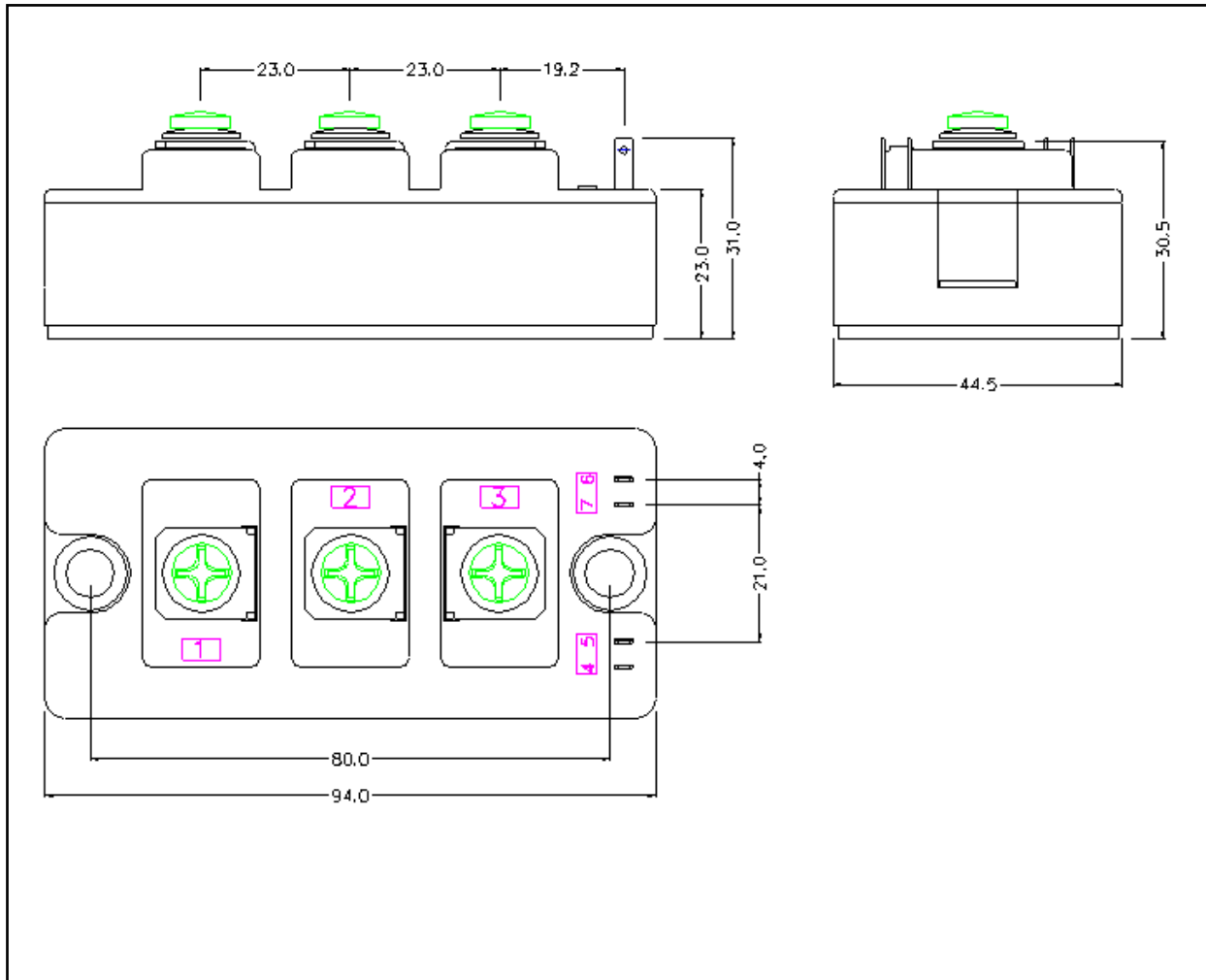
**Electrical Characteristics @ T<sub>J</sub>=25°C(unless otherwise specified)**

	Parameter	Min.	Typ.	Max.	Units	Conditions
V(BR)CES	Collector-to-Emitter Breakdown Voltage	600	—	—	V	V <sub>GE</sub> =0V, I <sub>C</sub> =1mA
V <sub>CE(ON)</sub>	Collector-to-Emitter Voltage	—	1.8	—		V <sub>GE</sub> =15V, I <sub>C</sub> =200A
		—	1.8	—		V <sub>GE</sub> =15V, I <sub>C</sub> =200A, T <sub>J</sub> =125°C
V <sub>GE(th)</sub>	Gate Threshold Voltage	4.0	—	6.0		I <sub>C</sub> =1.0mA
DV <sub>GE(th)</sub> DT <sub>J</sub>	Temperature Coeff. of Threshold Voltage	—	—	—	mV/°C	V <sub>CE</sub> =V <sub>GE</sub> , I <sub>C</sub> =0.75mA
g <sub>fe</sub>	Forward Transconductance	—	187	—	S	V <sub>CE</sub> =V <sub>GE</sub> , I <sub>C</sub> =200A
I <sub>CES</sub>	Collector - to - Emitter Leaking Current	—	—	1.0	mA	V <sub>GE</sub> =0V, V <sub>CE</sub> =600V
		—	—	2.0		V <sub>GE</sub> =0V, V <sub>CE</sub> =600V, T <sub>J</sub> =125°C
V <sub>FM</sub>	Diode Forward Voltage - Maximum	—	1.4	2.0	V	I <sub>F</sub> =200A, V <sub>GE</sub> =0V
		—	1.4	—		I <sub>F</sub> =200A, V <sub>GE</sub> =0V, T <sub>J</sub> =125°C
I <sub>GES</sub>	Gate - to - Emitter Leakage Current	—	—	250	nA	V <sub>GE</sub> =± 20V

**Dynamic Characteristics - T<sub>J</sub>=125°C (unless otherwise specified)**

	Parameter	Min.	Typ.	Max.	Units	Conditions
Q <sub>g</sub>	Total gate charge ( turn - on )	—	820	930	nC	V <sub>CC</sub> = 400V V <sub>GE</sub> =15V
Q <sub>ge</sub>	Gate - Emitter charge ( turn - on )	—	162	256		I <sub>C</sub> =200A
Q <sub>gc</sub>	Gate - Collector charge ( turn - on )	—	380	640		T <sub>J</sub> =25°C
T <sub>d(on)</sub>	Turn - On Delay Time	—	—	160	nS	R <sub>G1</sub> =10Ω , R <sub>G2</sub> = 0Ω
t <sub>r</sub>	Rise Time	—	—	145		I <sub>C</sub> = 200A
T <sub>d(off)</sub>	Turn - Off Delay Time	—	—	336		V <sub>CC</sub> = 360V
t <sub>f</sub>	Fall Time	—	—	287		V <sub>GE</sub> =± 15V
E <sub>on</sub>	Turn - On Switching Energy	—	12	—	mJ	
E <sub>off(1)</sub>	Turn - Off Switching Energy	—	20	—		
E <sub>ts(1)</sub>	Total Switching Energy	—	32	33		
C <sub>ies</sub>	Input Capacitance	—	—	29000	pF	V <sub>GE</sub> = 0V
C <sub>oes</sub>	Output Capacitance	—	—	2100		V <sub>CC</sub> = 30V
C <sub>res</sub>	Reverse Transfer Capacitance	—	—	1100		f=1MHZ
t <sub>rr</sub>	Diode Reverse Recovery Time	—	—	140	nS	I <sub>C</sub> = 200A
I <sub>rr</sub>	Diode Peak Reverse Current	—	—	100	A	R <sub>G1</sub> =27Ω
Q <sub>rr</sub>	Diode Recovery Charge	—	4000	—	nC	R <sub>G2</sub> =0Ω
di(rec)M/dt	Diode Peak Rate of Fall of Recovery During t <sub>b</sub>	—	4680	—	A/μs	V <sub>CC</sub> =360V di/dt=1400A/μs

**Case Outline**



Dimensions are shown in millimeters

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